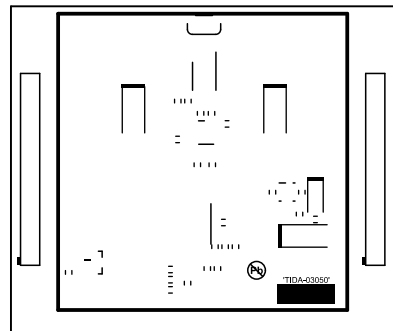
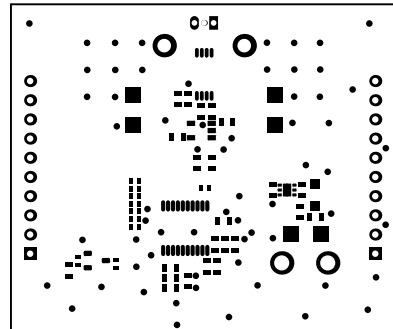


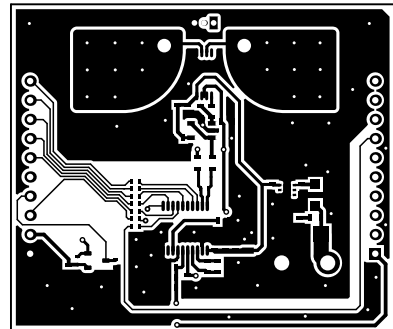
For evaluation only; not FCC approved for resale.



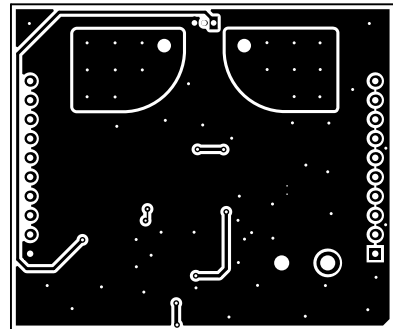
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03050	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-03050		
PLOT NAME = Top Overlay	GENERATED : 9/25/2017 2:16:39 PM	TEXAS INSTRUMENTS	



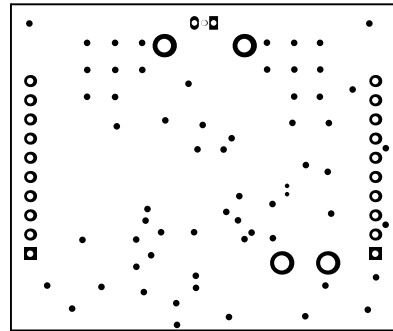
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03050	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-03050		
PLOT NAME = Top Solder Mask	GENERATED : 9/25/2017 2:16:40 PM	TEXAS INSTRUMENTS	



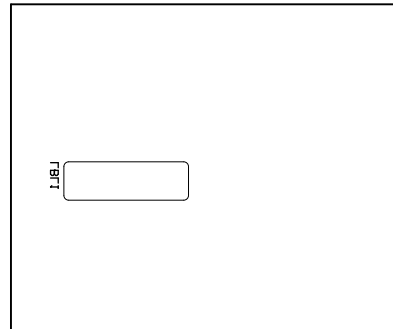
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LAYER NAME = Top Layer	TID #: TIDA-03050		
PLOT NAME = Top Layer	GENERATED : 9/25/2017 2:16:41 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03050	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-03050		
PLOT NAME = Bottom Layer	GENERATED : 9/25/2017 2:16:42 PM	TEXAS INSTRUMENTS	

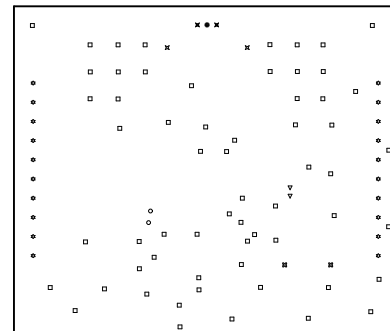


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03050	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-03050		
PLOT NAME = Bottom Solder Mask	GENERATED : 9/25/2017 2:16:43 PM	TEXAS INSTRUMENTS	

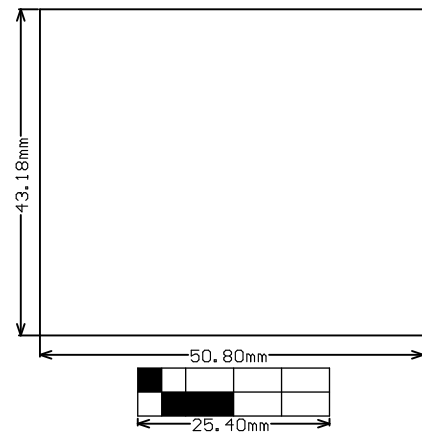


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03050	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-03050		
PLOT NAME = Bottom Overlay	GENERATED : 9/25/2017 2:16:43 PM		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊕	1	29.53mil (0.750mm)	NPTH	Round	Top Layer - Bottom Layer	
▽	2	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	2	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
□	61	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	20	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	70.87mil (1.800mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	
	92 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03050	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-03050		
PLOT NAME = Drill Drawing	GENERATED : 9/25/2017 2:16:44 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-03050	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-03050		
PLOT NAME = Board Dimensions	GENERATED : 9/25/2017 2:16:46 PM	TEXAS INSTRUMENTS	

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